



ULTRA-LOW VOLTAGE PROCESSOR SUPERVISORY CIRCUITS

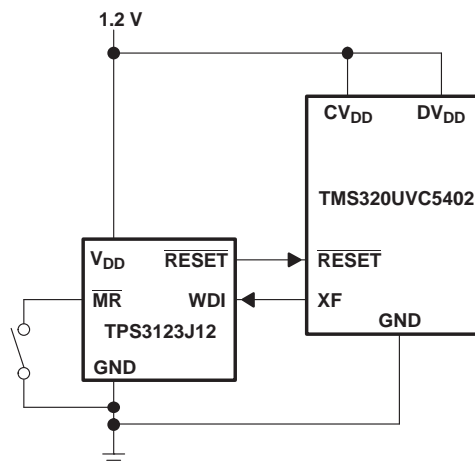
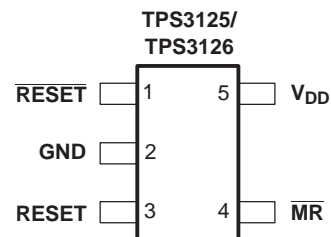
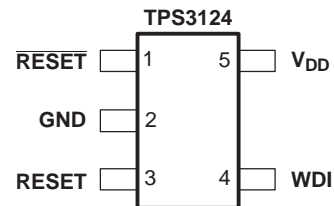
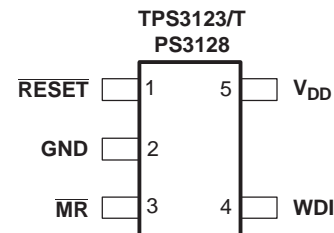
 Check for Samples: [TPS3123-xx](#), [TPS3124-xx](#), [TPS3125-xx](#), [TPS3126-xx](#), [TPS3128-xx](#)

FEATURES

- Minimum Supply Voltage of 0.75 V
- Supply Voltage Supervision Range:
 - 1.2 V, 1.5 V, 1.8 V (TPS312x)
 - 3 V (TPS3125 Devices Only)
 - Other Versions on Request
- Power-On Reset Generator With Fixed Delay Time of 180 ms
- Manual Reset Input (TPS3123/5/6/8)
- Watchdog Timer Retriggeres the $\overline{\text{RESET}}$ Output at $V_{\text{DD}} \geq V_{\text{IT}}$
- Supply Current of 14 μA (Typ)
- Small SOT23-5 Package
- Temperature Range of -40°C to $+85^\circ\text{C}$
- Reset Output Available in Push-Pull (Active Low and High) and Open-Drain (Active-Low)

APPLICATIONS

- Applications Using Low Voltage DSPs, Microcontrollers, or Microprocessors
- Portable/Battery-Powered Equipment
- Wireless Communication Systems
- Programmable Controls
- Industrial Equipment
- Notebook/Desktop Computers
- Intelligent Instruments

**DBV PACKAGE
(TOP VIEW)**

Figure 1. Typical Low-Voltage DSP Application


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DESCRIPTION

The TPS312x family of ultralow voltage processor supervisory circuits provides circuit initialization and timing supervision, primarily for DSP and processor-based systems.

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage (V_{DD}) becomes higher than 0.75 V. Thereafter, the supply voltage supervisor monitors V_{DD} and keeps $\overline{\text{RESET}}$ output active as long as V_{DD} remains below the threshold voltage (V_{IT}). An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_d = 180$ ms, starts after V_{DD} has risen above the threshold voltage (V_{IT}).

When the supply voltage drops below the threshold voltage (V_{IT}), the output becomes active (low) again. No external components are required. All the devices of this family have a fixed-sense threshold voltage (V_{IT}) set by a high precision internal voltage divider.

The TPS3123/5/6/8 devices incorporate a manual reset input, $\overline{\text{MR}}$. A low level at $\overline{\text{MR}}$ causes $\overline{\text{RESET}}$ to become active. The TPS3124 devices do not have the input MR, but include a high-level output RESET same as the TPS3125 and TPS3126 devices. In addition, the TPS3123/4/8 have a watchdog timer that needs to be triggered periodically by a positive or negative transition at $\overline{\text{WDI}}$. When the supervising system fails to retrigger the watchdog circuit within the time-out interval $t_{\text{out}} = 0.8$ s, $\overline{\text{RESET}}$ output becomes active for the time period (t_d). This event also reinitializes the watchdog timer.

The circuits are available in a 5-pin SOT23-5 package. The TPS312x devices are characterized for operation over a temperature range of -40°C to $+85^\circ\text{C}$.

Table 1. PACKAGE INFORMATION, STANDARD VERSIONS⁽¹⁾⁽²⁾

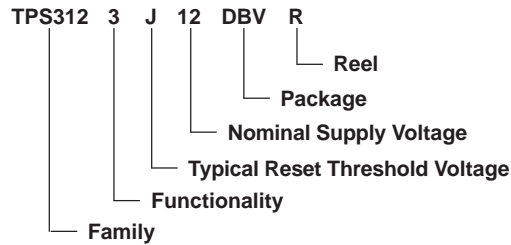
T_A	DEVICE NAME		THRESHOLD VOLTAGE	MARKING
-40°C to $+85^\circ\text{C}$	TPS3123J12DBVR ⁽³⁾	TPS3123J12DBVT ⁽⁴⁾	1.08 V	PBNI
	TPS3123G15DBVR ⁽³⁾	TPS3123G15DBVT ⁽⁴⁾	1.40 V	PBOI
	TPS3123J18DBVR ⁽³⁾	TPS3123J18DBVT ⁽⁴⁾	1.62 V	PBPI
	TPS3124J12DBVR ⁽³⁾	TPS3124J12DBVT ⁽⁴⁾	1.08 V	PBQI
	TPS3124G15DBVR ⁽³⁾	TPS3124G15DBVT ⁽⁴⁾	1.40 V	PBRI
	TPS3124J18DBVR ⁽³⁾	TPS3124J18DBVT ⁽⁴⁾	1.62 V	PBSI
	TPS3125J12DBVR ⁽³⁾	TPS3125J12DBVT ⁽⁴⁾	1.08 V	PBTI
	TPS3125G15DBVR ⁽³⁾	TPS3125G15DBVT ⁽⁴⁾	1.40 V	PBUI
	TPS3125J18DBVR ⁽³⁾	TPS3125J18DBVT ⁽⁴⁾	1.62 V	PBVI
	TPS3125L30DBVR ⁽³⁾	TPS3125L30DBVT ⁽⁴⁾	2.64 V	PBXI
	TPS3126E12DBVR ⁽³⁾	TPS3126E12DBVT ⁽⁴⁾	1.14 V	PFOI
	TPS3126E15DBVR ⁽³⁾	TPS3126E15DBVT ⁽⁴⁾	1.43 V	PFPI
	TPS3126E18DBVR ⁽³⁾	TPS3126E18DBVT ⁽⁴⁾	1.71 V	PFQI
	TPS3128E15DBVR ⁽³⁾	TPS3128E15DBVT ⁽⁴⁾	1.43 V	PFSI
TPS3128E18DBVR ⁽³⁾	TPS3128E18DBVT ⁽⁴⁾	1.71 V	PFTI	

(1) Other versions available. Contact Texas Instruments for details; minimum order quantities apply.

(2) For the most current package and ordering information see the Package Option Addendum at the end of this document, or visit the device product folder at www.ti.com.

(3) The DBVR passive indicates tape and reel of 3000 parts.

(4) The DBVT passive indicates tape and reel of 250 parts.


Table 2. Ordering Information Application Specific Versions ⁽¹⁾

DEVICE NAME	NOMINAL SUPPLY VOLTAGE, V_{NOM}	DEVICE NAME	TYPICAL RESET THRESHOLD VOLTAGE- V_{IT-}
TPS312xx12DBV	1.2 V	TPS312xAxxDBV	$V_{NOM} -1\%$
TPS312xx15DBV	1.5 V	TPS312xBxxDBV	$V_{NOM} -2\%$
TPS312xx18DBV	1.8 V	TPS312xCxxDBV	$V_{NOM} -3\%$
TPS312xx30DBV	3.0 V	TPS312xDxxDBV	$V_{NOM} -4\%$
		TPS312xExxDBV	$V_{NOM} -5\%$
		TPS312xFxxDBV	$V_{NOM} -6\%$
		TPS312xGxxDBV	$V_{NOM} -7\%$
		TPS312xHxxDBV	$V_{NOM} -8\%$
		TPS312xIxxDBV	$V_{NOM} -9\%$
		TPS312xJxxDBV	$V_{NOM} -10\%$
		TPS312xKxxDBV	$V_{NOM} -11\%$
		TPS312xLxxDBV	$V_{NOM} -12\%$
		TPS312xMxxDBV	$V_{NOM} -13\%$
		TPS312xNxxDBV	$V_{NOM} -14\%$
		TPS312xOxxDBV	$V_{NOM} -15\%$

(1) For the application-specific versions contact Texas Instruments for availability, lead time, and minimum order quantities.

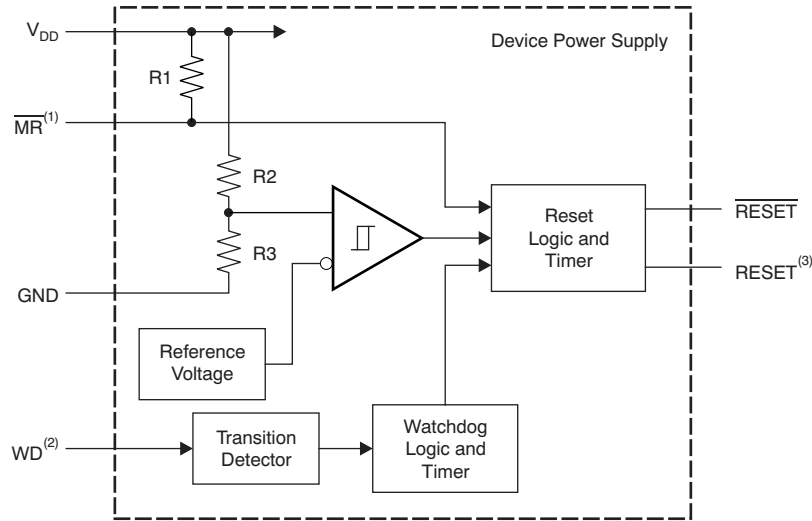
Table 3. Function Tables

TPS3123/8			TPS3124			TPS3125/6			
\overline{MR}	$V_{DD} > V_{IT}$	\overline{RESET}	$V_{DD} > V_{IT}$	\overline{RESET}	RESET	\overline{MR}	$V_{DD} > V_{IT}$	\overline{RESET}	RESET
L	0	L	0	L	H	L	0	L	H
L	1	L	1	H	L	L	1	L	H
H	0	L				H	0	L	H
H	1	H				H	1	H	L

Table 4. Reset Topology

DEVICES	OPEN DRAIN	PUSH-PULL
TPS3123		X
TPS3124		X
TPS3125		X
TPS3126	X	
TPS3128	X	

Figure 2. FUNCTIONAL BLOCK DIAGRAM



- NOTES:
 (1) TPS3123/5/6/8
 (2) TPS3123/4/8
 (3) TPS3124/5/6

Figure 3. TIMING DIAGRAM TPS3123/5/6/8

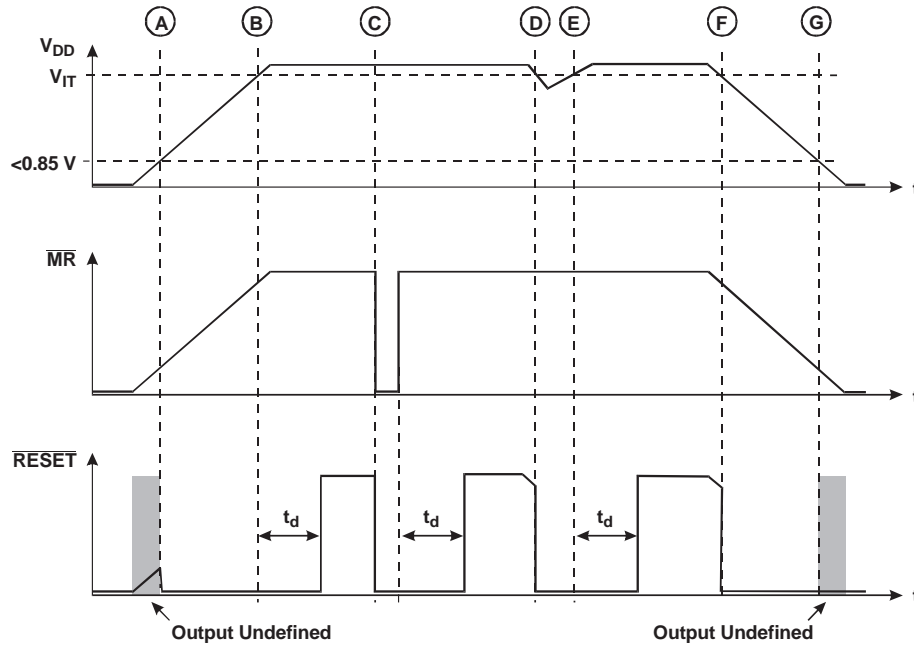
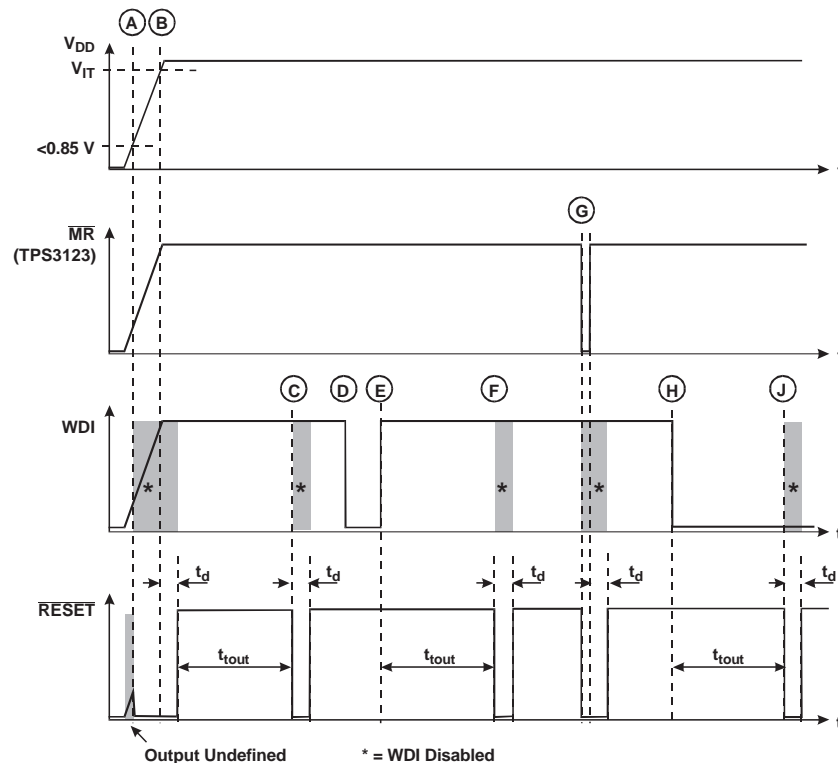


Figure 4. TIMING DIAGRAM TPS3123/4//8


ABSOLUTE MAXIMUM RATINGS

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	UNIT
Manual reset, $\overline{\text{MR}}$	–0.3 V to $V_{DD} + 0.6\text{ V}$
$\overline{\text{RESET}}$	–0.3 V to $V_{DD} + 0.6\text{ V}$
V_{DD} Supply voltage	3.6 V
WDI Watchdog input	–0.3 V to $V_{DD} + 0.6\text{ V}$
I_{OL} Maximum low output current	5 mA
I_{OH} Maximum high output current	–5 mA
I_{IK} Input clamp current ($V_I < 0$ or $V_I > V_{DD}$)	$\pm 10\text{ mA}$
I_{OK} Output clamp current ($V_O < 0$ or $V_O > V_{DD}$)	$\pm 10\text{ mA}$
Continuous total power dissipation	See Dissipation Rating Table
T_A Operating free-air temperature range,	–40°C to +85°C
T_{stg} Storage temperature range,	–65°C to +150°C
Soldering temperature	+260°C
Open drain RESET outputs	–0.3 V to $V_{DD} + 0.3\text{ V}$

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq +25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = +25^\circ\text{C}$	$T_A = +70^\circ\text{C}$ POWER RATING	$T_A = +85^\circ\text{C}$ POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

RECOMMENDED OPERATING CONDITIONS

at specified temperature range.

		MIN	MAX	UNIT
V _{DD}	Supply voltage	T _A = 0°C to +85°C		V
		T _A = -40°C to +85°C		
V _{DD}	Manual reset voltage	0.0	V _{DD} + 0.3	V
V _{WD1}	Watchdog input voltage	0	V _{DD} + 0.3	V
V _{IH}	High-level input voltage	0.7 × V _{DD}		V
V _{IL}	Low-level input voltage	0.3 × V _{DD}		V
Δ t/Δ V	Input transition rise and fall rate at WDI	1		μs/V
T _A	Operating free-air temperature range	40	+85	°C

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted).

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$\overline{\text{MR}}$ pullup resistor (internal)				27			kΩ
I _{IH}	High-level input current	WDI	WDI = V _{DD} = 3.3 V	1		1	μA
		$\overline{\text{MR}}$	$\overline{\text{MR}}$ = 0.7 × V _{DD} , V _{DD} = 3.3 V	20		55	
I _{IL}	Low-level input current	WDI	WDI = 0 V, V _{DD} = 3.3 V	1		1	μA
		$\overline{\text{MR}}$	$\overline{\text{MR}}$ = 0 V, V _{DD} = 3.3 V	80		170	
I _{OH}	High-level output current (leakage into $\overline{\text{RESET}}$ pin)	TPS3126-xx, TPS3128-xx	V _{DD} = V _{OH} = 3.3 V			200	nA
V _{OH}	High-level output voltage (TPS3123/4/5 only)	$\overline{\text{RESET}}$	V _{DD} = 1.5 V, I _{OH} = -1 mA	0.8 × V _{DD}			V
			V _{DD} = 3.3 V, I _{OH} = -4.5 mA				
		RESET	V _{DD} = 0.75 V, I _{OH} = -8 μA				
			V _{DD} = 1.5 V, I _{OH} = -1 mA				
V _{OL}	Low-level output voltage	$\overline{\text{RESET}}$	V _{DD} = 0.75 V, I _{OL} = 15 μA	0.2 × V _{DD}			V
			V _{DD} = 1.5 V, I _{OL} = 1.4 mA				
		RESET	V _{DD} = 1.5 V, I _{OL} = 1.4 mA				
			V _{DD} = 3.3 V, I _{OL} = 3 mA				
V _{IT-}	Negative-going input threshold voltage ⁽¹⁾	TPS312xJ12	T _A = -40°C to +85°C	1.04	1.08	1.12	V
		TPS312xG15		1.35	1.40	1.45	
		TPS312xJ18		1.56	1.62	1.68	
		TPS312xL30		2.57	2.64	2.71	
		TPS312xE12		1.10	1.14	1.18	
		TPS312xE15		1.38	1.43	1.48	
		TPS312xE18		1.65	1.71	1.77	
V _{hys}	Hysteresis at V _{DD} input	1 V < V _{IT-} < 1.4 V		15			mV
		1.4 V < V _{IT-} < 2 V		20			
		2 V < V _{IT-} < 3 V		30			
I _{DD}	Supply current	TPS3123-xx TPS3124-xx TPS3128-xx	WDI = V _{DD} , $\overline{\text{MR}}$ unconnected	V _{DD} = 0.75 V	14		μA
				V _{DD} = 3.3 V	22	30	
		TPS3125-xx TPS3126-xx ⁽²⁾	$\overline{\text{MR}}$ unconnected	V _{DD} = 0.75 V	14		
				V _{DD} = 3.3 V	18	25	
C _i	Input capacitance at $\overline{\text{MR}}$, WDI	V _I = 0 V to 3.3 V		5			pF

(1) To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1 μF) should be placed near the supply terminal.

(2) The supply current during delay time t_d is typical 5 μA higher.

TIMING REQUIREMENTS

 at $R_L = 1\text{ M}\Omega$, $C_L = 50\text{ pF}$, $T_A = +25^\circ\text{C}$.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_w	Pulse width	$V_{IH} = V_{IT-} + 0.2\text{ V}$, $V_{IL} = V_{IT-} - 0.2\text{ V}$	6			μs
	At V_{DD}		1			
	At $\overline{\text{MR}}$		0.1			
	At WDI	$V_{DD} \geq V_{IT-} + 0.2\text{ V}$, $V_{IL} = 0.3 \times V_{DD}$, $V_{IH} = 0.7 \times V_{DD}$				

SWITCHING CHARACTERISTICS

 at $R_L = 1\text{ M}\Omega$, $C_L = 50\text{ pF}$, $T_A = +25^\circ\text{C}$.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t_{tout}	Watchdog time out	$V_{DD} \geq V_{IT-} + 0.2\text{ V}$, See timing diagram	0.8	1.4	2.1	s	
t_d	Delay time	$V_{DD} > V_{IT-} + 0.2\text{ V}$, See timing diagram	100	180	260	ms	
t_{PHL}	Propagation delay time, high-to-low-level output	$\overline{\text{MR}}$ to $\overline{\text{RESET}}$ delay (TPS3123/5/6/8)	$V_{DD} \geq V_{IT-} + 0.2\text{ V}$, $V_{IL} = 0.2 \times V_{DD}$, $V_{IH} = 0.8 \times V_{DD}$			0.1	μs
t_{PLH}	Propagation delay time, low-to-high-level output	$\overline{\text{MR}}$ to $\overline{\text{RESET}}$ delay (TPS3125/6)				0.1	
t_{PHL}	Propagation delay time, high-to-low-level output	V_{DD} to $\overline{\text{RESET}}$ delay	$V_{IL} = V_{IT-} - 0.2\text{ V}$, $V_{IH} = V_{IT-} + 0.2\text{ V}$			10	μs
t_{PLH}	Propagation delay time, low-to-high-level output	V_{DD} to $\overline{\text{RESET}}$ delay (TPS3124/5/6)				10	

TYPICAL CHARACTERISTICS

SUPPLY CURRENT
 vs
 SUPPLY VOLTAGE

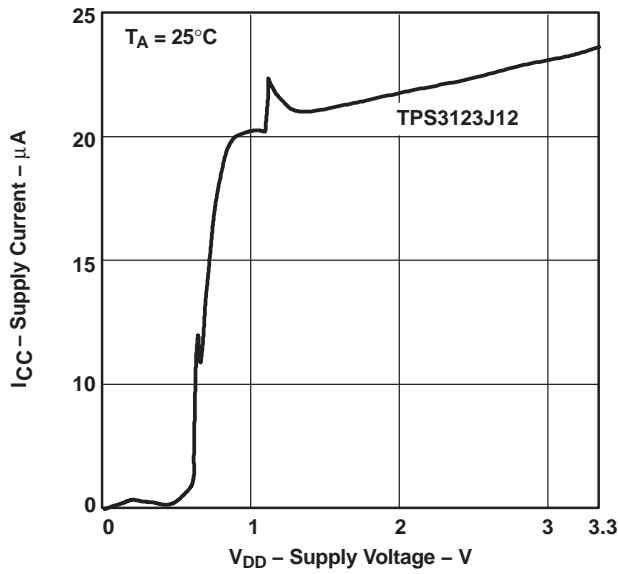


Figure 5.

LOW-LEVEL OUTPUT VOLTAGE
 vs
 LOW-LEVEL OUTPUT CURRENT

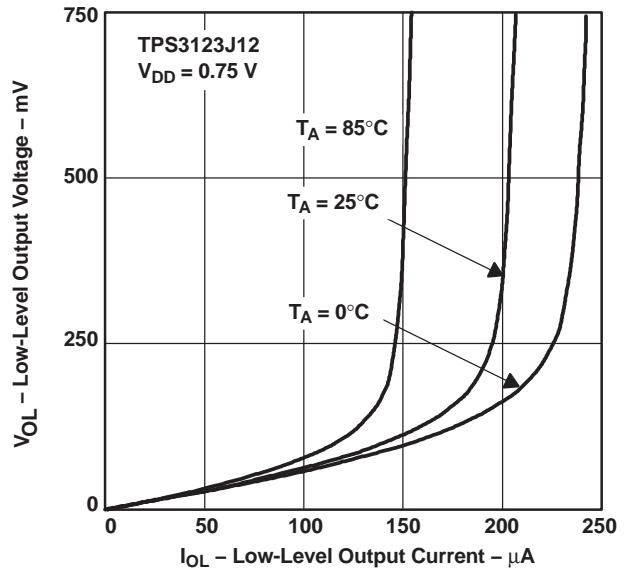


Figure 6.

LOW-LEVEL OUTPUT VOLTAGE
 vs
 LOW-LEVEL OUTPUT CURRENT

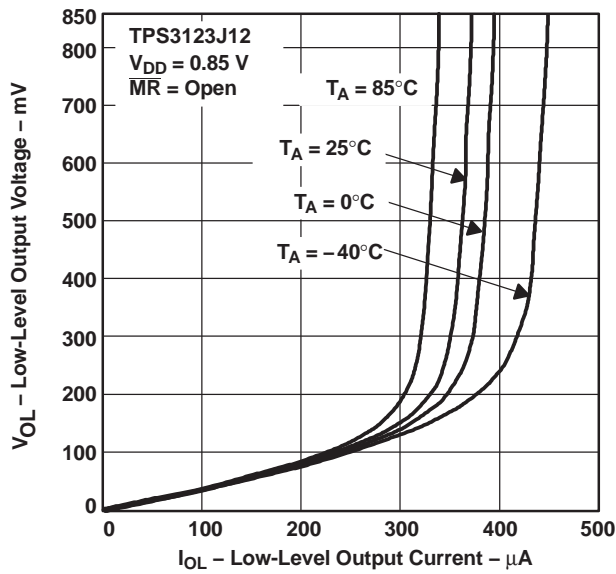


Figure 7.

LOW-LEVEL OUTPUT VOLTAGE
 vs
 LOW-LEVEL OUTPUT CURRENT

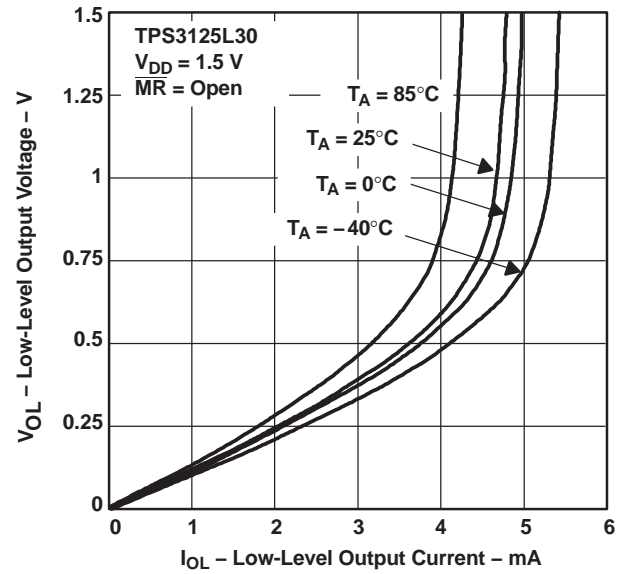


Figure 8.

TYPICAL CHARACTERISTICS (continued)

LOW-LEVEL OUTPUT VOLTAGE
 vs
 LOW-LEVEL OUTPUT CURRENT

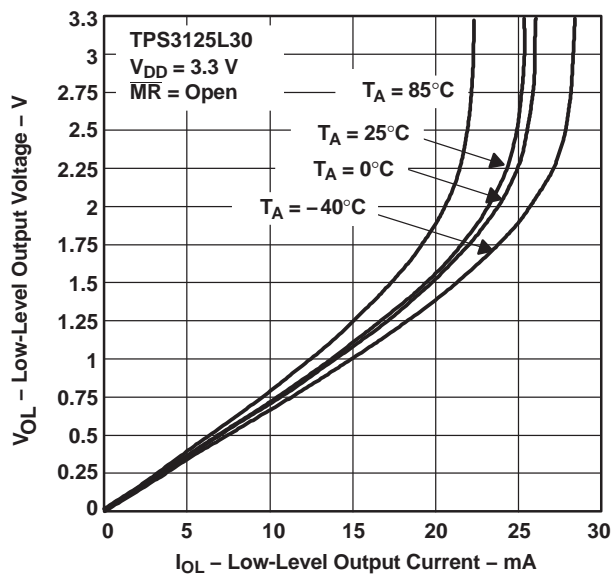


Figure 9.

HIGH-LEVEL OUTPUT VOLTAGE
 vs
 HIGH-LEVEL OUTPUT CURRENT

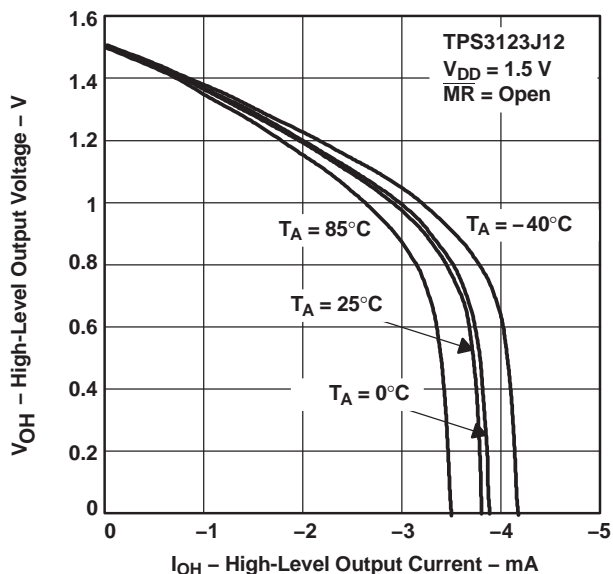


Figure 10.

HIGH-LEVEL OUTPUT VOLTAGE
 vs
 HIGH-LEVEL OUTPUT CURRENT

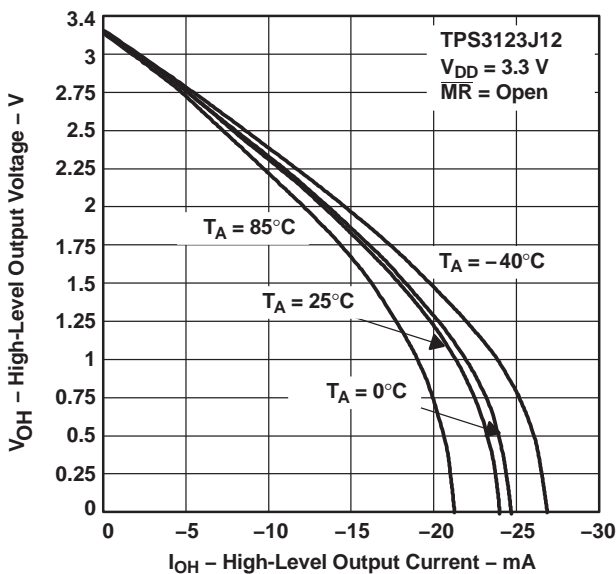


Figure 11.

NORMALIZED INPUT THRESHOLD VOLTAGE
 vs
 FREE-AIR TEMPERATURE

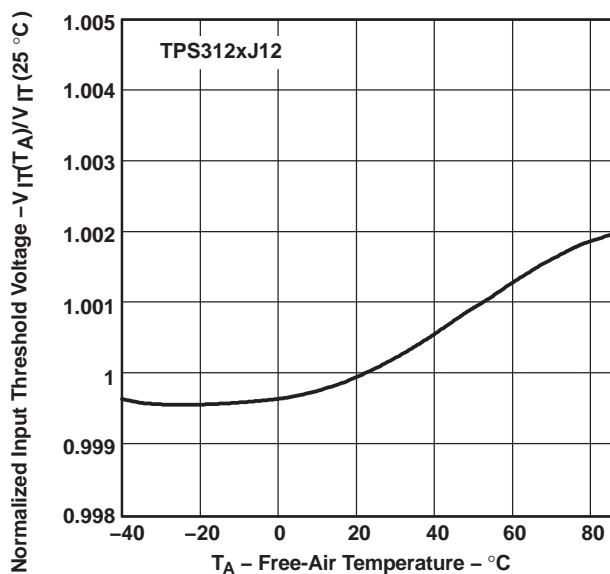


Figure 12.

TYPICAL CHARACTERISTICS (continued)

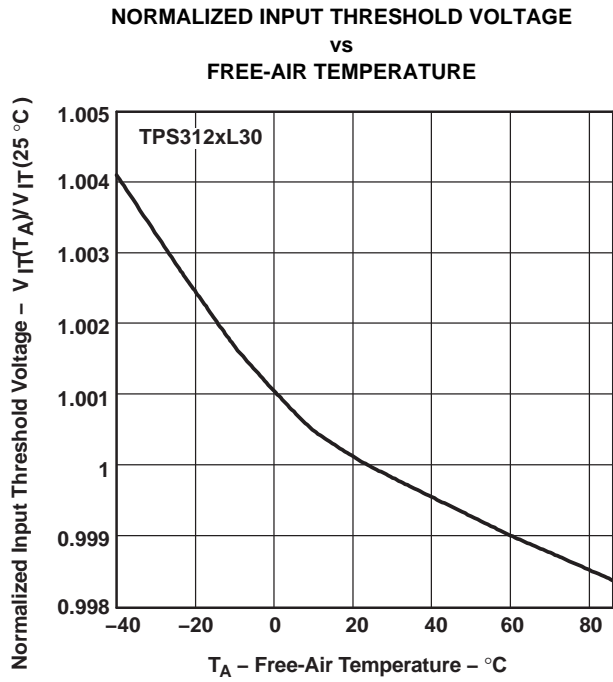


Figure 13.

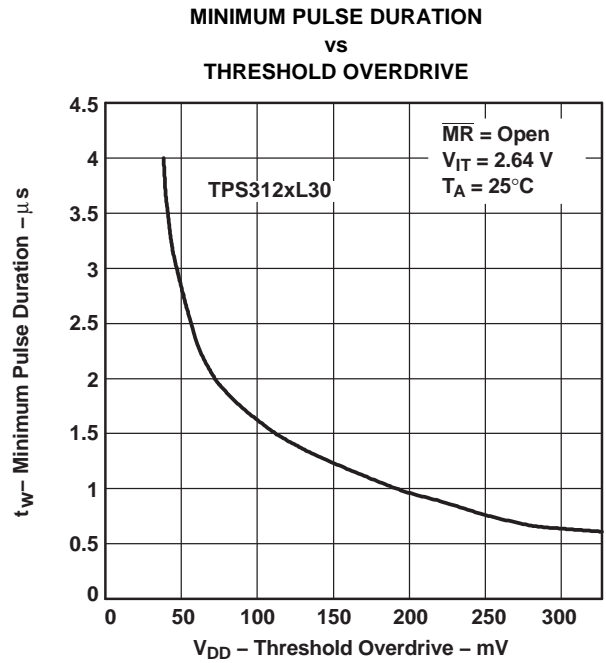


Figure 14.

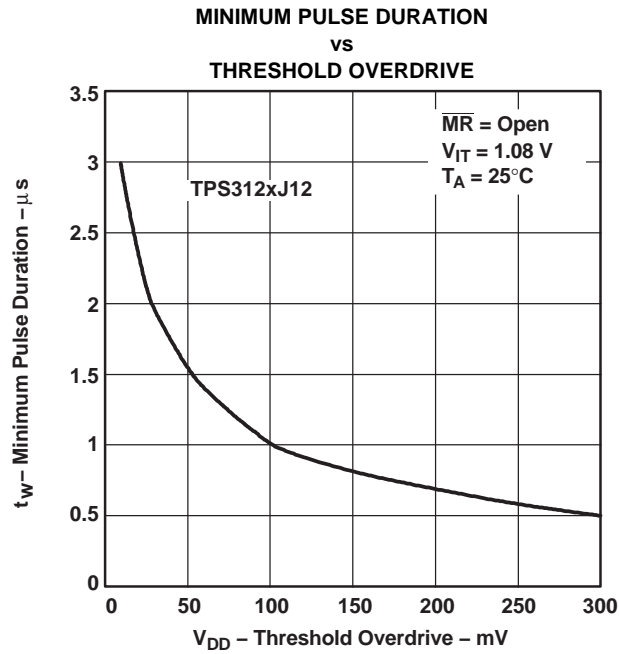


Figure 15.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision D (December, 2006) to Revision E	Page
• Removed <i>TPS3128E12DBVR</i> from list of orderable devices in Table 1	2

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3123J12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBNI	Samples
TPS3123J12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBNI	Samples
TPS3123J12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBNI	Samples
TPS3123J18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBPI	Samples
TPS3123J18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBPI	Samples
TPS3123J18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBPI	Samples
TPS3124G15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBRI	Samples
TPS3124J12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBQI	Samples
TPS3124J12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBQI	Samples
TPS3124J12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBQI	Samples
TPS3124J18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBSI	Samples
TPS3124J18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBSI	Samples
TPS3124J18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBSI	Samples
TPS3125G15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Samples
TPS3125G15DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Samples
TPS3125G15DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Samples
TPS3125G15DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBUI	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3125J12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J12DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBTI	Samples
TPS3125J18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125J18DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125J18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125J18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBVI	Samples
TPS3125L30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3125L30DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3125L30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3125L30DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PBXI	Samples
TPS3126E12DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E12DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFOI	Samples
TPS3126E15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFPI	Samples
TPS3126E15DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFPI	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS3126E15DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFPI	Samples
TPS3126E18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFQI	Samples
TPS3126E18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFQI	Samples
TPS3126E18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFQI	Samples
TPS3128E12DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFRI	Samples
TPS3128E12DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFRI	Samples
TPS3128E15DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFSI	Samples
TPS3128E15DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFSI	Samples
TPS3128E18DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples
TPS3128E18DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples
TPS3128E18DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples
TPS3128E18DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PFTI	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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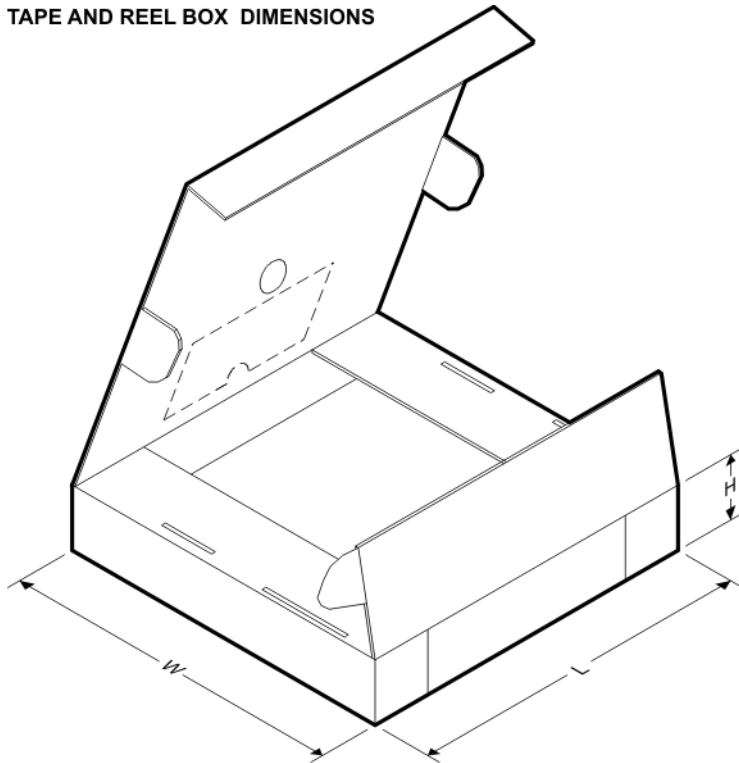
TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3123J12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3123J12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3123J18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3123J18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124G15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3124J18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125G15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125G15DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125J18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125L30DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3125L30DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E12DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3126E12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E15DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3126E18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E12DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E15DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E15DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E18DBVR	SOT-23	DBV	5	3000	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3
TPS3128E18DBVT	SOT-23	DBV	5	250	180.0	9.0	3.15	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3123J12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3123J12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3123J18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3123J18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3124G15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3124J12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3124J12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3124J18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3124J18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125G15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125G15DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125J12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125J12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125J18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125J18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3125L30DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3125L30DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3126E12DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3126E12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3126E15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3126E15DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3126E18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3126E18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3128E12DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3128E15DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3128E15DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0
TPS3128E18DBVR	SOT-23	DBV	5	3000	182.0	182.0	20.0
TPS3128E18DBVT	SOT-23	DBV	5	250	182.0	182.0	20.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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